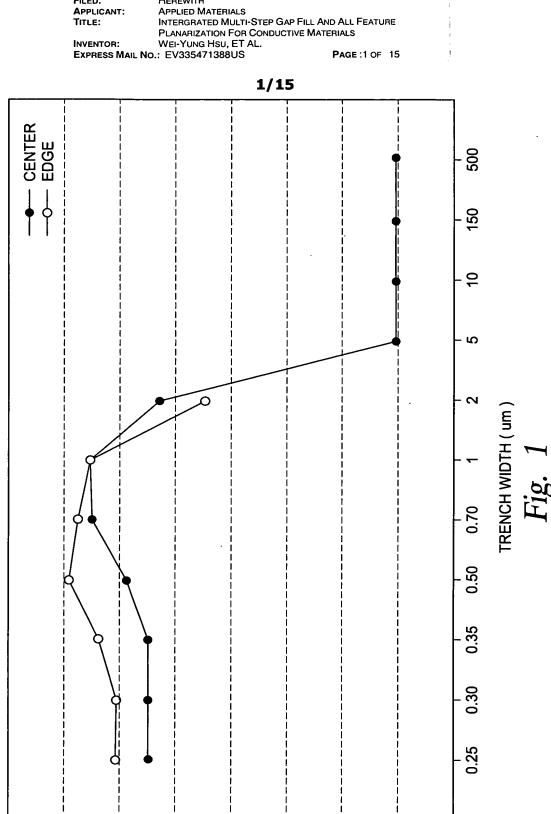
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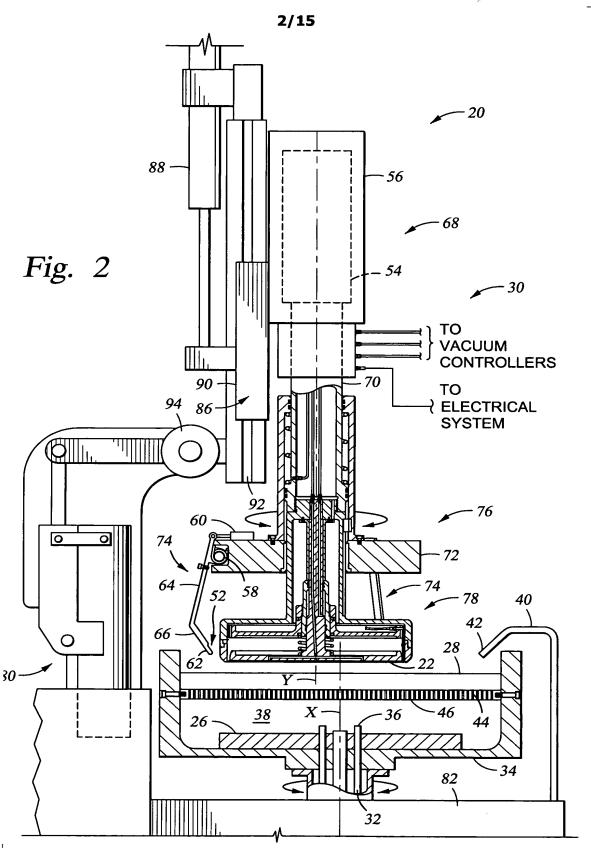
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PLANARIZATION FOR CONDUCTIVE MATERIALS

WEI-YUNG HSU, ET AL.

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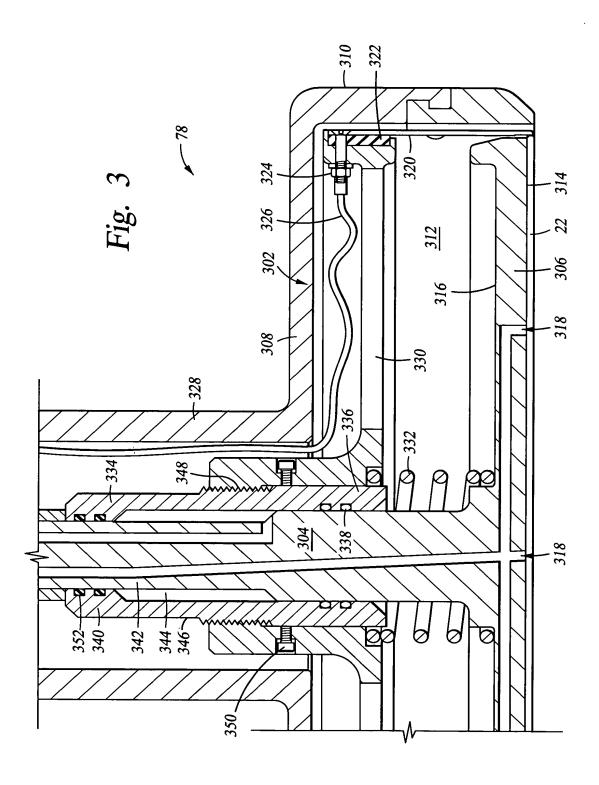
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PLANARIZATION FOR CONDUCTIVE MATERIALS
INVENTOR: WEI-YUNG HSU, ET AL.
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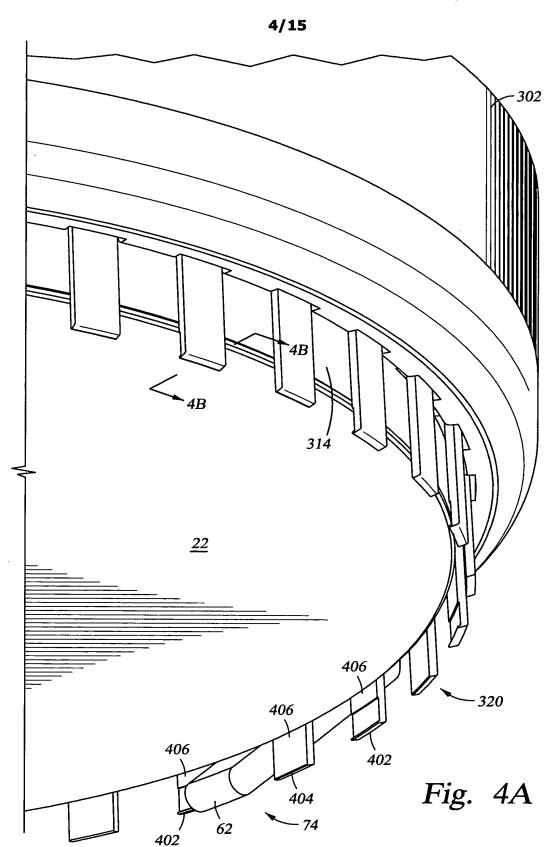


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INVENTOR: WEI-YUNG HSU, ET AL.
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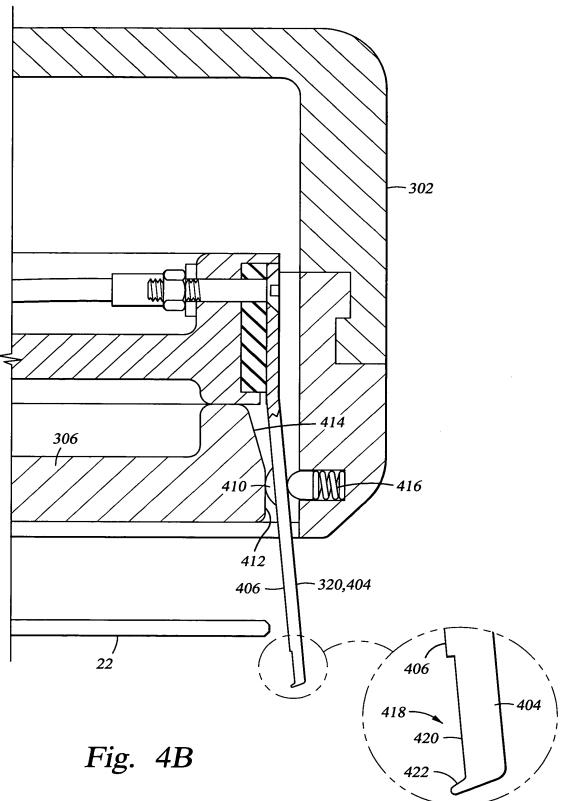
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WEI-YUNG HSU, ET AL. INVENTOR:

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INVENTOR: WEI-YUNG HSU, ET AL.
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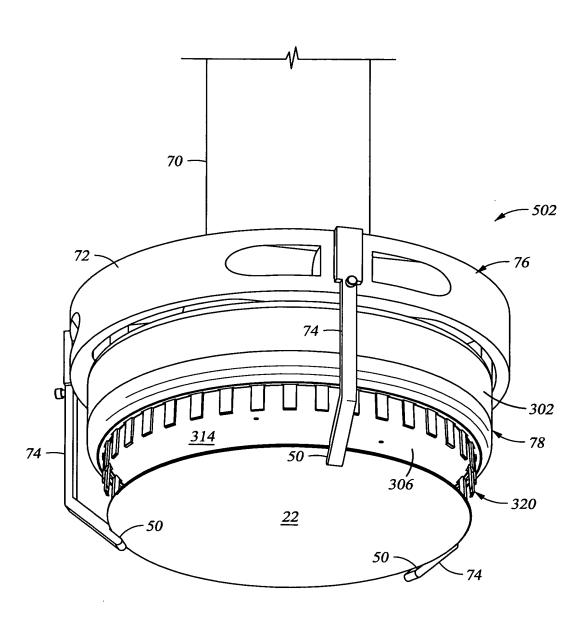


Fig. 5A

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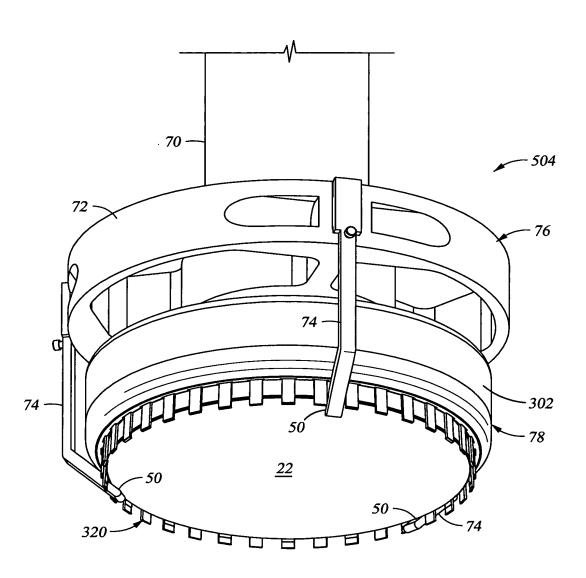


Fig. 5B

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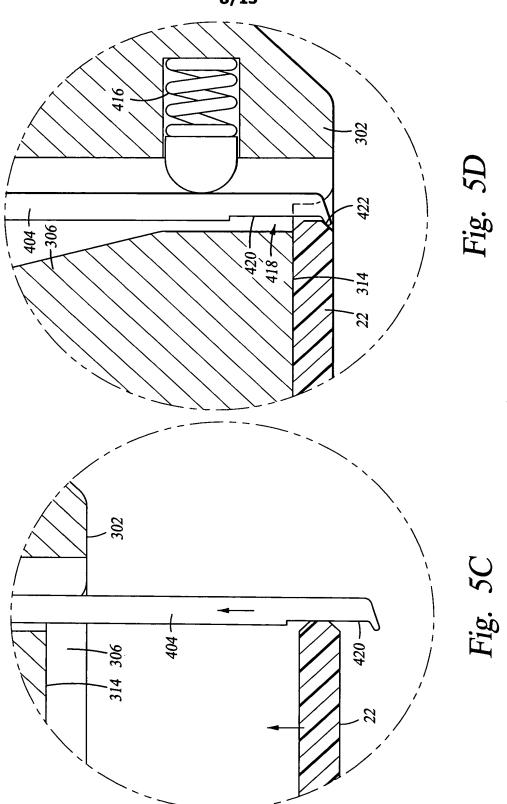
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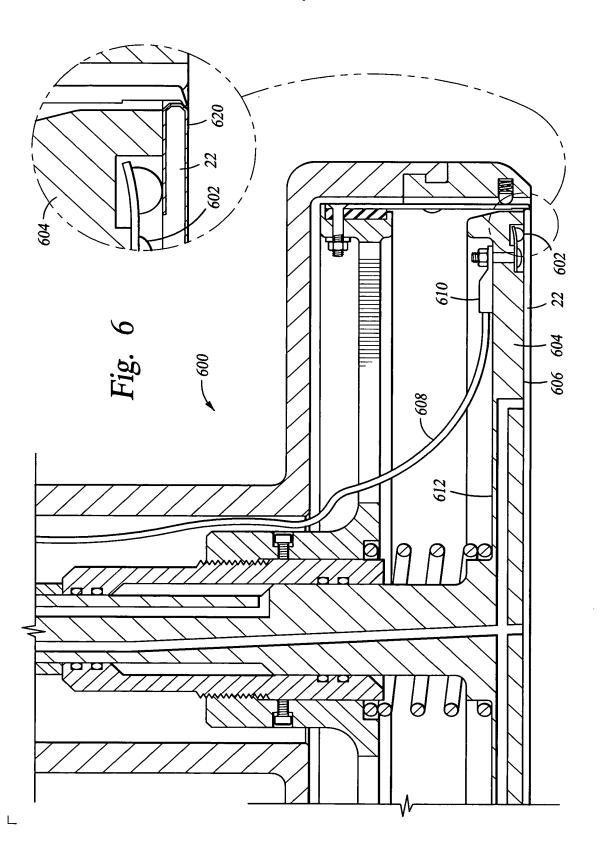
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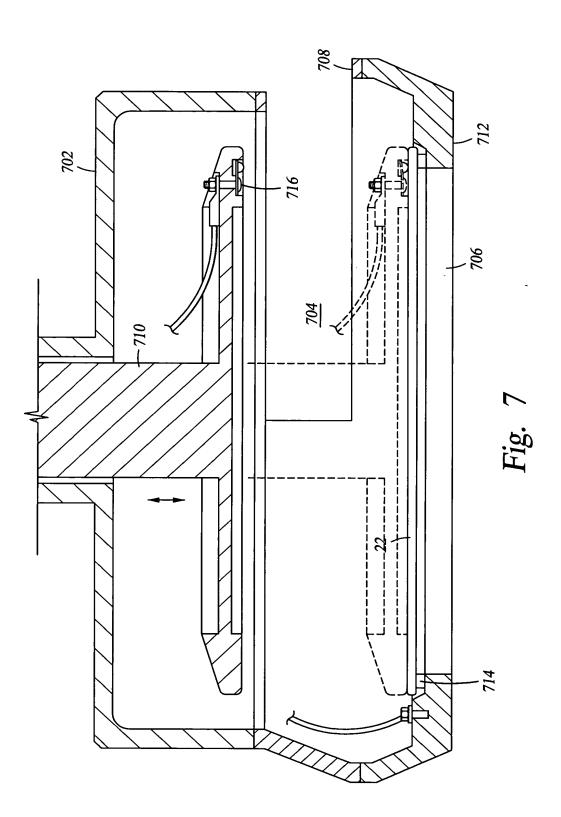
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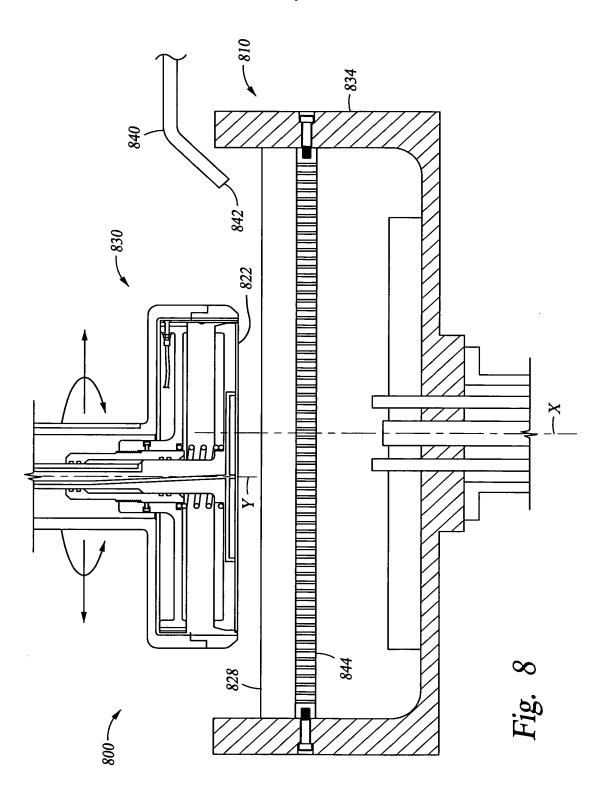
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PLANARIZATION FOR CONDUCTIVE MATERIALS

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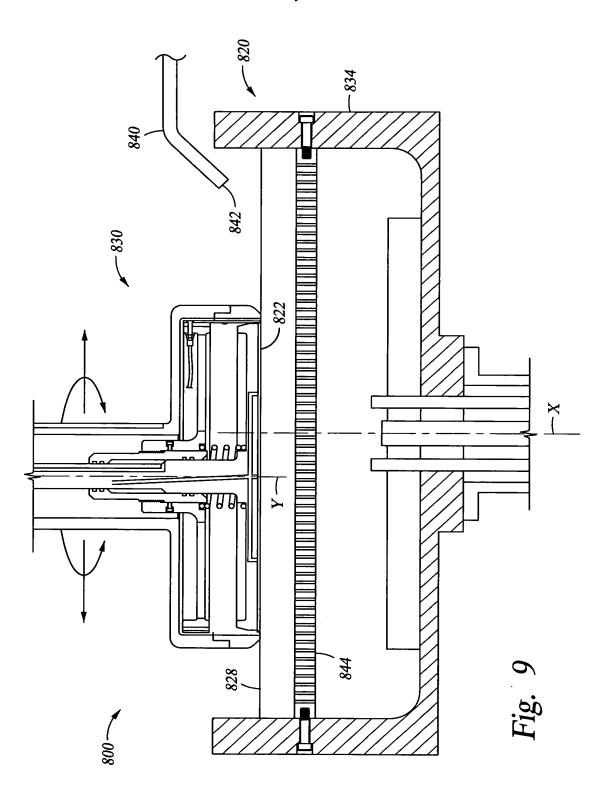
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PLANARIZATION FOR CONDUCTIVE MATERIALS

INVENTOR: WEI-YUNG HSU, ET AL.

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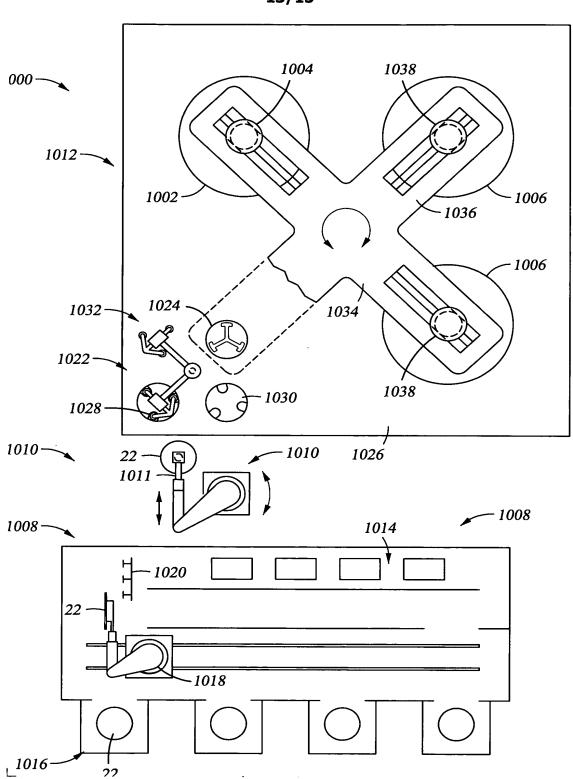
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WEI-YUNG HSU, ET AL. TITLE:

INVENTOR:

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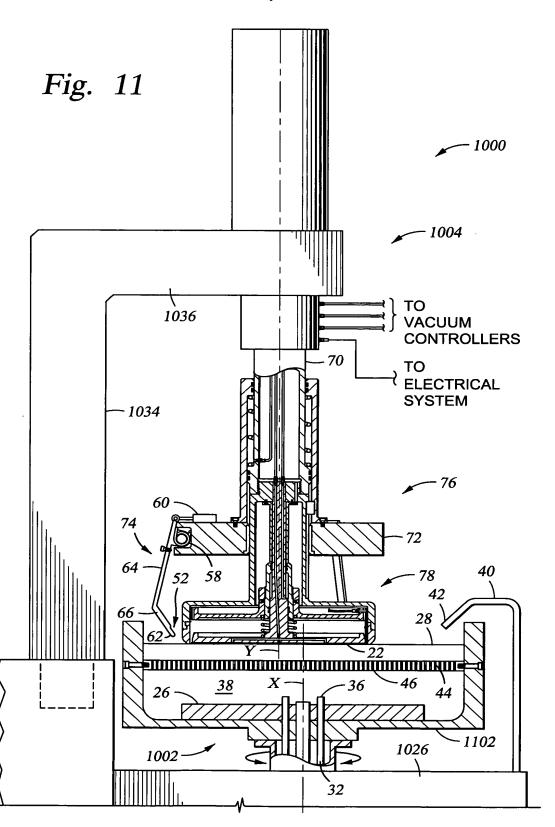
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PLANARIZATION FOR CONDUCTIVE MATERIALS

INVENTOR: WEI-YUNG HSU, ET AL.

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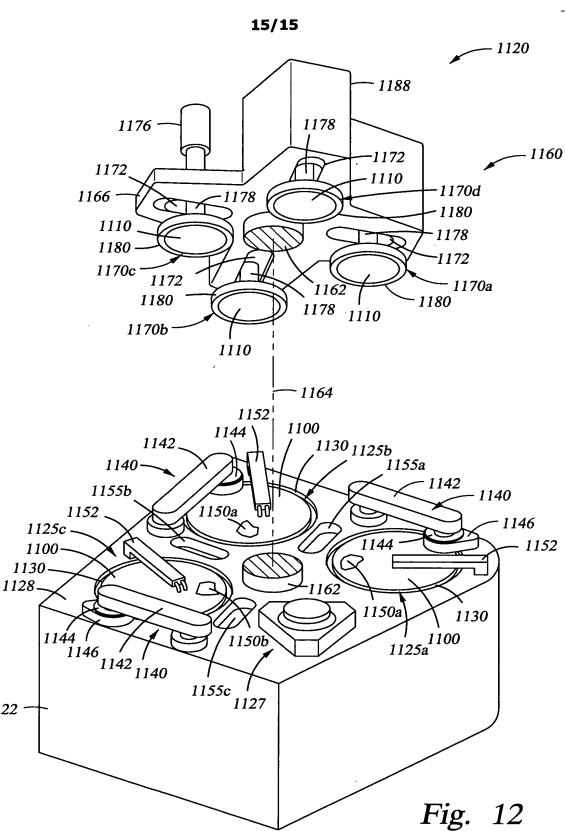
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